

**Molex 55091-0274 PDF**

**molex<sup>®</sup>**

深圳创唯电子有限公司

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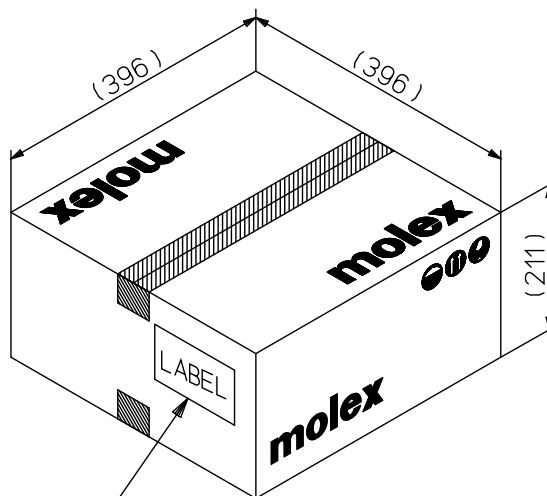
1. 製品名称／PRODUCT NAME : 0.635 PITCH B-TO-B S/T PLUG HS'G ASSY EMBOSSED TAPE PACKAGING  
 製品番号／PART NUMBER : 5 5 0 9 1 - \* \* 3 0  
 5 5 0 9 1 - \* \* 7 4  
 ( \* \* は極数を示す)  
 ( \* \* SHOWS CIRCUITS SIZE)

2. 標準梱包数／STANDARD PACKAGING QUANTITY

| 極数<br>CKT.<br>SIZE | キャリア<br>テープ幅 (mm)<br>CARRIER TAPE<br>WIDTH (mm) | 1 リール中の製品数<br>QTY. PER REEL | 外装カートン<br>SHIPPING CARTON |                 |
|--------------------|---|-----------------------------|---------------------------|-----------------|
|                    |   |                             | 梱包リール数<br>NUMBER OF REELS | 製品数<br>QUANTITY |
| 20                 | 24  | 1,000                       | 6                         | 6,000           |
| 30                 | 32  | 1,000                       | 4                         | 4,000           |
| 40                 |   |                             |                           |                 |
| 50                 | 44  | 1,000                       | 3                         | 3,000           |
| 60                 |   |                             |                           |                 |
| 70                 |   |                             |                           |                 |
| 80                 |   |                             |                           |                 |
| 90                 | 56  | 1,000                       | 3                         | 3,000           |
| 100                |   |                             |                           |                 |
| 120                | 72  | 1,000                       | 2                         | 2,000           |
| 140                |   |                             |                           |                 |
| 160                |   |                             |                           |                 |
| 200                | 88  | 1,000                       | 1                         | 1,000           |

|                              |  |        |  |                           |                       |                     |  |                 |  |
|------------------------------|--|--------|--|---------------------------|-----------------------|---------------------|--|-----------------|--|
| REV.                         | B  |        |  |                           |                       |                     |  |                 |  |
| SHEET                        | 1~2  |        |  |                           |                       |                     |  |                 |  |
| REVISE ON PC ONLY            |  |        | TITLE:   |                           |                       |                     |  |                 |  |
| <b>B</b>                     | REVISED<br>600158<br>2018/05/07 Y.TOKUZONO |        | 5 5 0 9 1 梱包仕様書<br>SALES PACKAGING SPEC. FOR 55091   |                           |                       |                     |  |                 |  |
|                              |  |        | THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION |                           |                       |                     |  |                 |  |
| REV.                         | DESCRIPTION                                |        |  |                           |                       |                     |  |                 |  |
| DESIGN CONTROL<br>J          |  | STATUS | WRITTEN BY:<br>T.NAKAGAWA01  | CHECKED BY:<br>T.HARUYAMA | APPROVED BY:<br>Y.ITO | DATE:<br>2016/04/28 |  |                 |  |
| DOCUMENT NUMBER<br>550919200 |  |        | DOC. TYPE<br>PS  | DOC. PART<br>200          | CUSTOMER<br>GENERAL   |                     |  | SHEET<br>1 OF 2 |  |

3. カートン外形参考寸法 / CARTON OUTER DIMENSIONS (REFERENCE PURPOSE ONLY)      単位 / UNIT: mm



カートンラベル  
CARTON LABEL

(製品型番, 数量, ロットNO. 表示)  
INDICATION OF PART No., QUANTITY, LOT No.

標準カートン  
STANDARD CARTON

|                              |                  |  |                  |                     |
|------------------------------|------------------|--|------------------|---------------------|
| REVISE ON PC ONLY            |                  | TITLE:   |                  |                     |
| <b>B</b>                     | SEE SHEET 1 OF 2 | 5 5 0 9 1 梱包仕様書<br>SALES PACKAGING SPEC. FOR 55091   |                  |                     |
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|                              |                  |  |                  | SHEET<br>2 OF 2     |

**【1. 適用範囲 SCOPE】**

本仕様書は、                                    殿 に納入する 0.635 mm ピッチ 基板対基板用コネクタ について規定する。  
This product specification covers the performance requirements for 0.635 mm PITCH BOARD TO BOARD CONNECTOR series.

**【2. 製品名称及び型番 PRODUCT NAME AND PART NUMBER】**

**2-1. 型番詳細 DETAIL OF PART NUMBER**

| 製品名称<br>Product Name                      | 嵌合高さ<br>Stacking Height | 吸着カバー有無<br>Cover         | 製品番号<br>Material Number | エンボス梱包<br>Embossed Packaging | スティック梱包<br>Stick Packaging |
|---|-------------------------|--------------------------|-------------------------|------------------------------|----------------------------|
| リセプタクル<br>アセンブリ<br>Receptacle<br>Assembly | H=6~10mm                | 吸着カバー無し<br>Without Cover | 52760-**70              | 52760-**78                   | 52760-**79                 |
|   |                         | 吸着カバー付き<br>With Cover    | 52885-**72              | 52885-**74                   | -                          |
|   | H=12~16mm               | 吸着カバー無し<br>Without Cover | 52837-**70              | 52837-**78                   | 52837-**79                 |
|   |                         | 吸着カバー付き<br>With Cover    | 52901-**72              | 52901-**74                   | -                          |
| プラグ<br>アセンブリ<br>Plug<br>Assembly          | H=6,12mm                | 吸着カバー無し<br>Without Cover | 55091-**71              | -                            | 55091-**79                 |
|   |                         | 吸着カバー付き<br>With Cover    | 55091-**72              | 55091-**74                   | 55091-**75                 |
|   | H=7,13mm                | 吸着カバー無し<br>Without Cover | 53481-**77              | -                            | 53481-**79                 |
|   |                         | 吸着カバー付き<br>With Cover    | 53625-**72              | 53625-**74                   | -                          |
|   | H=8,14mm                | 吸着カバー無し<br>Without Cover | 53551-**77              | 53551-**78                   | 53551-**79                 |
|   |                         | 吸着カバー付き<br>With Cover    | 53647-***9              | 53647-**74                   | 53647-**75                 |
|   | H=9,15mm                | 吸着カバー付き<br>With Cover    | 53649-**72              | 53649-**74                   | 53649-**75                 |
|   | H=10,16mm               | 吸着カバー無し<br>Without Cover | 53553-**77              | 53553-**78                   | 53553-**79                 |
| 吸着カバー付き<br>With Cover                     |                         | 53627-**72               | 53627-**74              | 53627-**75                   |                            |

\*\* : 図面参照 Refer to the drawing.

|  |      |             |      |      |  |  |  |  |  |                  |  |                        |  |                         |  |                           |  |                     |  |  |  |
|--|------|-------------|------|------|--|--|--|--|--|------------------|--|------------------------|--|-------------------------|--|---------------------------|--|---------------------|--|--|--|
| REV.   | 0    | A           | B    | C    |  |  |  |  |  |                  |  |                        |  |                         |  |                           |  |                     |  |  |  |
| SHEET  | 1-18 | 1-18        | 1-18 | 1-18 |  |  |  |  |  |                  |  |                        |  |                         |  |                           |  |                     |  |  |  |
| REVISE ON PC ONLY  |      |             |      |      |  |  |  | TITLE:<br>0.635 BOARD TO BOARD CONNECTOR   |  |                  |  |                        |  |                         |  |                           |  |                     |  |  |  |
| <b>C</b><br>変更<br>REVISED<br>EC NO. : 602629<br>2018/08/17 RMIAYMOTO |      |             |      |      |  |  |  | <b>PRODUCT SPECIFICATION</b>   |  |                  |  |                        |  |                         |  |                           |  |                     |  |  |  |
|  |      |             |      |      |  |  |  | THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION |  |                  |  |                        |  |                         |  |                           |  |                     |  |  |  |
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| DESIGN CONTROL<br>J  |      |             |      |      |  |  |  | STATUS   |  |                  |  | WRITTEN BY:<br>YSATO06 |  | CHECKED BY:<br>TASAKAWA |  | APPROVED BY:<br>KMORIKAWA |  | DATE:<br>2016/03/18 |  |  |  |
| DOCUMENT NUMBER<br>527600000   |      |             |      |      |  |  |  | DOC. TYPE<br>PS  |  | DOC. PART<br>000 |  | CUSTOMER<br>GENERAL    |  |                         |  | SHEET<br>1 OF 18          |  |                     |  |  |  |

2-2. 嵌合高さ詳細 DETAIL OF STACKING HEIGHT

| 嵌合高さ<br>Stacking Height | リセプタクル アッセンブリ<br>Receptacle Assembly | プラグ アッセンブリ<br>Plug Assembly |
|-------------------------|--------------------------------------|-----------------------------|
| H=6mm                   | 52760/52885 series                   | 55091 series                |
| H=7mm                   |                                      | 53481/53625 series          |
| H=8mm                   |                                      | 53551/53647 series          |
| H=9mm                   |                                      | 53649 series                |
| H=10mm                  |                                      | 53553/53627 series          |
| H=12mm                  | 52837/52901 series                   | 55091 series                |
| H=13mm                  |                                      | 53481/53625 series          |
| H=14mm                  |                                      | 53551/53647 series          |
| H=15mm                  |                                      | 53649 series                |
| H=16mm                  |                                      | 53553/53627 series          |

|                              |                   |  |  |                     |                  |
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| EN-127(2015-12)              |                   |  |  |                     |                  |

**【3. 定 格 RATINGS】**

| 項 目<br>Item   |                   | 規 格<br>Standard   |                     |
|---|-------------------|---|---------------------|
| 最大許容電圧<br>Rated Voltage (MAXIMUM)                   |                   | 100V  | [AC (実効値 rms) / DC] |
| 最大許容電流<br>Rated Current (MAXIMUM)                   |                   | 0.5A  |                     |
| 使用温度範囲 <sup>*1</sup><br>Operating Temperature Range |                   | -55°C ~ +105°C <sup>*2</sup>                                      |                     |
| 保管条件<br>Storage Condition                           | 温度<br>Temperature | -10°C ~ +50°C   |                     |
|   | 湿度<br>Humidity    | 85%R.H.以下 (但し結露しないこと)<br>85%R.H. MAX. (No Condensation)           |                     |
|   | 期間<br>Terms       | 出荷後6ヶ月 (未開封の場合)<br>For 6 months after shipping (unopened package) |                     |

\*1 : 基板実装後の無通電状態は、使用温度範囲が適用されます。

Non-operating connectors after reflow must follow the operating temperature range condition.

\*2 : 通電による温度上昇分を含む。

This includes the terminal temperature rise generated by conducting electricity.

**【4. 性 能 PERFORMANCE】**

標準状態 ; 特に指定がない限り、測定は温度 15~35°C、湿度 25~85%、気圧 86~106kPa にて行う。

但し、判定に疑義を生じた場合は、温度 20±1°C、湿度 63~67%、気圧86~106kPa にて行う。

Standard atmospheric conditions;

Unless otherwise specified, the standard range of atmospheric conditions for making measurements and tests are as follows.

Ambient temperature : 15°C to 35°C  
Relative humidity : 25% to 85%  
Air pressure : 86kPa to 106kPa

If there is any doubt about the results, measurements shall be made by the following test conditions.

Ambient temperature : 20±1°C  
Relative humidity : 63% to 67%  
Air pressure : 86kPa to 106kPa

|                              |                   |                                |                              |                     |                  |
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| EN-127(2015-12)              |                   |                                |                              |                     |                  |

4-1. 電気的性能 Electrical Performance

| 項目<br>Item |                               | 条件<br>Test Condition  | 嵌合高さ<br>Stacking Height                     | 規格<br>Requirement      |
|------------|-------------------------------|---|---|------------------------|
| 4-1-1      | 接触抵抗<br>Contact Resistance    | コネクタを嵌合させ、開放電圧 20mV 以下、<br>短絡電流 10mA以下にて測定する。<br>(JIS C5402 5.4)<br>Mate connectors, measured at the open circuit<br>voltage 20mV MAXIMUM and short circuit 10mA<br>MAXIMUM.<br>(JIS C5402 5.4)                           | H= 6 ~ 7mm                                  | 40 milliohm<br>MAXIMUM |
|            |                               |   | H= 8 ~ 10mm                                 | 50 milliohm<br>MAXIMUM |
|            |                               |   | H= 12 ~ 13mm                                | 60 milliohm<br>MAXIMUM |
|            |                               |   | H= 14 ~ 16mm                                | 70 milliohm<br>MAXIMUM |
| 4-1-2      | 絶縁抵抗<br>Insulation Resistance | コネクタを嵌合させ、隣接するターミナル間に、<br>DC250V を印加し測定する。<br>(JIS C5402 5.2/MIL-STD-202 試験法 302)<br>Mate connectors, measured by applying DC 250V<br>between adjacent terminal.<br>(JIS C5402 5.2/MIL-STD-202 Method 302)                | 1000 Megohm MINIMUM                         |                        |
| 4-1-3      | 耐電圧<br>Dielectric Strength    | コネクタを嵌合させ、隣接するターミナル間に、<br>AC 250V [実効値] を<br>1分間 印加する。<br>(JIS C5402 5.1/MIL-STD-202 試験法 301)<br>Mate connectors, apply 250V AC[rms] for<br>1 minute between adjacent terminal.<br>(JIS C5402 5.1/MIL-STD-202 Method 301) | 製品機能を損なう<br>異状なきこと<br>No Damage on function |                        |
| 4-1-4      | 温度上昇<br>Temperature Rise      | コネクタを嵌合させ、最大許容電流を<br>通電し、コネクタの温度上昇分を測定する。<br>Mate connectors, measure the temperature rise of<br>connector when the maximum AC rated current is<br>passed.  | 温度上昇<br>Temperature Rise                    | 30 °C<br>MAXIMUM       |

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TITLE:

0.635 BOARD TO BOARD CONNECTOR

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4-2. 機械的性能 Mechanical Performance

| 項目<br>Item  | 条件<br>Test Condition  | 規格<br>Requirement  |
|---|---|--|
| 4-2-1<br>挿入力及び抜去力<br>Insertion and<br>Withdrawal Force  | 毎分 25±3mm の速さで挿入、抜去を行う。<br>Insert and withdraw connectors,<br>at the speed rate of 25±3mm/minute.               | 挿入力<br>Insertion Force<br>0.690N {70gf} / CIRCUIT<br>MAXIMUM |
|   |   | 抜去力<br>Withdrawal<br>Force<br>0.118N {12gf} / CIRCUIT        |
| 4-2-2<br>端子保持力<br>Terminal / Housing<br>Retention Force | ハウジングに装着された端子を毎分 25±3mm の速さで引張る。<br>Pull the terminal mated with the housing at the speed of 25±3mm per minute. | 1.96N {0.2 kgf}<br>MINIMUM                                   |

4-3. 耐久性能 Durability Performances

| 項目<br>Item   | 条件<br>Test Condition   | 規格<br>Requirement  |
|--|--|--|
| 4-3-1<br>繰返し挿抜<br>Repeated Insertion /<br>Withdrawal | 無通電状態にて1分間 10回以下の速さで挿入、抜去を 50回 繰返す。<br>When mated up to 50 cycles repeatedly by the rate of 10 cycles per minute in the power-off state.   | 接触抵抗<br>Contact<br>Resistance<br>初期規格値からの変化量:<br>20 milliohm以下<br>Change from initial<br>requirement :<br>20 milliohm<br>MAXIMUM |
| 4-3-2<br>耐振動性<br>Vibration                           | コネクタを嵌合させ、DC 1mA通電状態にて、嵌合軸を含む互いに垂直な3方向に掃引割合 10~55~10Hz/分、全振幅1.5mmの振動を各2時間加える。<br>(MIL-STD-202試験法 201)<br>Mate connectors and subject to the following vibration conditions, for a period of 2 hours in each of 3 mutually perpendicular axes, passing DC 1mA during the test.<br>Amplitude : 1.5mm P-P<br>Frequency : 10-55-10Hz / minute<br>(MIL-STD-202, Method 201) | 外観<br>Appearance<br>製品機能を損なう<br>異状なきこと<br>No Damage on function  |
|  |  | 接触抵抗<br>Contact<br>Resistance<br>初期規格値からの変化量:<br>20 milliohm以下<br>Change from initial<br>requirement :<br>20 milliohm<br>MAXIMUM |
|  |  | 瞬断<br>Discontinuity<br>0.1microsecond<br>MAXIMUM   |

REVISE ON PC ONLY

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TITLE:

0.635 BOARD TO BOARD CONNECTOR

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|-------|--------------------------|---|-------------------------------|--|
| 4-3-3 | 耐衝撃性<br>Mechanical Shock | コネクタを嵌合させ、DC 1mA 通電状態にて、嵌合軸を含む互いに垂直な 6方向に 490m/s <sup>2</sup> { 50G } の衝撃を作用時間11ミリ秒で各3回 加える。<br>(JIS C60068-2-27/MIL-STD-202 試験法 213)<br>Mate connectors, add to each 3 times with impact of 490m/s <sup>2</sup> {50G}on action time 11milliseconds at 6 directions mutually vertical including fitting axis in DC 1 mA electricity state. (JIS C60068-2-27/MIL-STD-202 Method 213) | 外 観<br>Appearance             | 製品機能を損なう<br>異状なきこと<br>No Damage on function  |
|       |                          |   | 接 触 抵 抗<br>Contact Resistance | 初期規格値からの変化量:<br>20 milliohm以下<br>Change from initial requirement :<br>20 milliohm<br>MAXIMUM |
|       |                          |   | 瞬 断<br>Discontinuity          | 0.1 microsecond<br>MAXIMUM   |
| 4-3-4 | 耐熱性<br>Heat Resistance   | コネクタを嵌合させ、105±2°C の雰囲気中に 96時間 放置後取り出し、1~2時間 室温に放置する。<br>(JIS C60068-2-2/MIL-STD-202 試験法 108)<br>Mate connectors, exposing for 96 hours in the atmosphere of 105±2 degree C. After the test, allowed to stand at room temperature for 1 to 2 hours before checking functionality. (JIS C60068-2-2/MIL-STD-202 Method 108)  | 外 観<br>Appearance             | 製品機能を損なう<br>異常なきこと<br>No Damage on function  |
|       |                          |   | 接 触 抵 抗<br>Contact Resistance | 初期規格値からの変化量:<br>20 milliohm以下<br>Change from initial requirement :<br>20 milliohm<br>MAXIMUM |

|  |                   |                                |
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| 項目<br>Item |                                  | 条件<br>Test Condition  | 規格<br>Requirement                |   |
|------------|----------------------------------|---|----------------------------------|---|
| 4-3-5      | 耐寒性<br>Cold Resistance           | コネクタを嵌合させ、-55±3°Cの<br>雰囲気中に96時間放置後取り出し、<br>1~2時間室温に放置する。<br>(JIS C60068-2-1)<br>Mate connectors, exposing -55±3 degree C<br>for 96 hours. Upon completion of the<br>exposure period, the test specimens shall<br>be conditioned at ambient room conditions<br>for 1 to 2 hours, after which the specified<br>measurements shall be performed.<br>(JIS C60068-2-1)   | 外観<br>Appearance                 | 製品機能を損なう<br>異状なきこと<br>No Damage on function   |
|            |                                  |   | 接触抵抗<br>Contact<br>Resistance    | 初期規格値からの変<br>化量:<br>20 milliohm以下<br>Change from initial<br>requirement :<br>20 milliohm<br>MAXIMUM |
| 4-3-6      | 耐湿性<br>Humidity                  | コネクタを嵌合させ、60±2°C、<br>相対湿度90~95%の雰囲気中に<br>96時間放置後取り出し、1~2時間<br>室温に放置する。<br>(JIS C60068-2-3/MIL-STD-202 試験法103)<br>Mate connectors, exposing for 96 hours in<br>an atmosphere of 60±2 degree C, relative<br>humidity 90 to 95%. After the test, allowed<br>to stand at room temperature for 1 to 2<br>hours before checking functionality.<br>(JIS C60068-2-3/MIL-STD-202 Method 103)   | 外観<br>Appearance                 | 製品機能を損なう<br>異状なきこと<br>No Damage on function   |
|            |                                  |   | 接触抵抗<br>Contact<br>Resistance    | 初期規格値からの変<br>化量:<br>20 milliohm以下<br>Change from initial<br>requirement :<br>20 milliohm<br>MAXIMUM |
|            |                                  |   | 耐電圧<br>Dielectric<br>Strength    | 4-1-3項 満足のこと<br>Must meet 4-1-3   |
|            |                                  |   | 絶縁抵抗<br>Insulation<br>Resistance | 100 Megohm<br>MINIMUM   |
| 4-3-7      | 温度サイクル<br>Temperature<br>Cycling | コネクタを嵌合させ、-55±3°Cに30分、<br>85±2°Cに30分これを1サイクルとし、<br>5サイクル繰返す。但し、温度移行時間は5<br>分以内とする。試験後1~2時間室温に放置<br>する。<br>(JIS C60068-2-14)<br>Mate connectors, exposing to 85±2 degree<br>C and -55±3 degree C temperature<br>extremes for 30 minutes each including a<br>0-5 minutes transition time. The<br>above-mentioned condition is repeated 5<br>cycles. After the test, allowed to stand at<br>the room temperature for 1 to 2 hours<br>before checking functionality.<br>(JIS C60068-2-14) | 外観<br>Appearance                 | 製品機能を損なう<br>異状なきこと<br>No Damage on function   |
|            |                                  |   | 接触抵抗<br>Contact<br>Resistance    | 初期規格値からの変<br>化量:<br>20 milliohm以下<br>Change from initial<br>requirement :<br>20 milliohm<br>MAXIMUM |

REVISE ON PC ONLY

TITLE:

0.635 BOARD TO BOARD CONNECTOR

**C**

SEE SHEET 1 OF 18

**PRODUCT SPECIFICATION**

THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

REV.

DESCRIPTION

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| 項目<br>Item |                                       | 条件<br>Test Condition   | 規格<br>Requirement          |  |
|------------|---------------------------------------|--|----------------------------|--|
| 4-3-8      | 塩水噴霧<br>Salt Spray                    | コネクタを嵌合させ、35±2°C にて 5±1% 重量比 の塩水を 48±4時間 噴霧し、試験後常温で水洗いした後、室温で乾燥させる。<br>(JIS C60068-2-11/MIL-STD-202 試験法 101)<br>Mate connectors, exposing to the atmosphere where salt mist is diffused in.<br>Other condition is written below.<br>NaCl solution : 5±1% by weight<br>Temperature : 35±2 degree C<br>Duration : 48 hours<br>After the test, they should be washed well by water and dried at room temperature before checking functionality.<br>(JIS C60068-2-11/MIL-STD-202 Method 101) | 外観<br>Appearance           | 製品機能を損なう<br>異状なきこと<br>No Damage on function  |
|            |                                       |  | 接触抵抗<br>Contact Resistance | 初期規格値からの変化量:<br>20 milliohm以下<br>Change from initial requirement :<br>20 milliohm MAXIMUM          |
| 4-3-9      | 亜硫酸ガス<br>SO <sub>2</sub> Gas          | コネクタを嵌合させ、40±2°C にて 50±5ppm の亜硫酸ガス中に 24時間 放置する。<br>Mate connectors, exposing to the atmosphere is written below.<br>Gas Concentration : SO <sub>2</sub> =50±5ppm<br>Temperature : 40±2 degree C<br>Duration : 24h  | 外観<br>Appearance           | 製品機能を損なう<br>異状なきこと<br>No Damage on function  |
|            |                                       |  | 接触抵抗<br>Contact Resistance | 初期規格値からの変化量:<br>20 milliohm以下<br>Change from initial requirement :<br>20 milliohm MAXIMUM          |
| 4-3-10     | 半田付け性<br>Solderability                | 端子先端より0.5mmの位置まで245±3°Cの半田に3±0.5秒浸す。<br>Dip soldertails into the molten solder {held at 245±3 degree C }up to 0.5mm from the bottom of the housing for 3±0.5 seconds   | 濡れ性<br>Solder Wetting      | 浸漬した金または錫めつき面積の95%以上<br>95% of immersed gold or Tin plating area must show no voids, no pin holes. |
| 4-3-11     | 半田耐熱性<br>Resistance to Soldering Heat | 赤外線リフロー時 Infrared Reflow Method<br>第6項参照 2回リフロー実施<br>Refer to the paragraph 6<br>2 times reflow enforcement  | 外観<br>Appearance           | 製品機能を損なう<br>異状なきこと<br>No Damage on function  |
|            |                                       | 手半田時 Hand Soldering Method<br>端子先端より0.5mm、金具先端より0.5mmの位置まで385±15°Cの半田ゴテにて最大5秒加熱する。<br>但し、異常な加圧がないこと。<br>Heat the position of 0.5mm from terminal tip and 0.5mm from fitting nail tip for 5 seconds with 385±15 degree C soldering iron.<br>However, without too much pressure to the terminal pin and fitting nail.  |                            |  |

|  |                   |                                |
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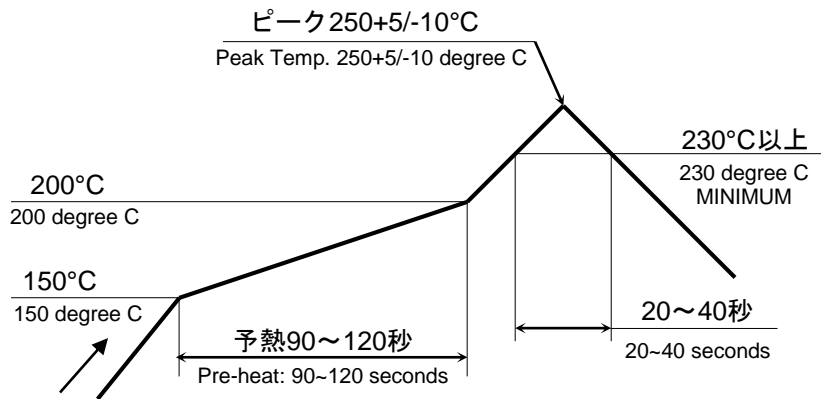
【5. 外観形状、寸法及び材質 PRODUCT SHAPE, DIMENSIONS AND MATERIALS】

図面参照 Refer to the drawing.

ELV 及び RoHS適合品 ELV AND RoHS COMPLIANT.

|                 |                   |                   |           |          |   |
|-----------------|-------------------|-------------------|-----------|----------|---|
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【6. 赤外線リフロー条件 INFRARED REFLOW CONDITION】



温度条件グラフ  
TEMPERATURE CONDITION GRAPH

半田接合部の基板表面にて測定  
(Temperature is measured at the soldering area on the surface of the P.W. Board.)

注記：本リフロー条件に関しては、温度プロファイル、半田ペースト、大気、N<sub>2</sub>リフロー、基板などにより条件が異なりますので事前に実装評価（リフロー評価）を必ず実施願います。実装条件によっては、製品性能に影響を及ぼす場合があります。

NOTE: Please investigate the mounting condition (reflow soldering condition) on your own devices beforehand. The mounting conditions may change due to the soldering temperature, soldering paste, air reflow machine, Nitrogen reflow machine, and the type of P.W. Board. The different mounting conditions may have an influence on the product's performance.

推奨ランド寸法：図面をご参照ください

参考メタルマスク厚さ：t=0.10[mm]

参考メタルマスク開口率：100%（大気リフロー時）

Recommended land dimension: Please refer to the drawing.

Referenced Metal mask thickness: t = 0.10[mm].

Referenced Metal mask aperture rate:100% (at air reflow).

|                   |                   |  |                              |          |                 |
|-------------------|-------------------|--|------------------------------|----------|-----------------|
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【8. 取り扱い上の注意事項 INSTRUCTION UPON USAGE】

[嵌合]

嵌合は極力嵌合軸に沿って平行に行ってください。(図-1)  
 その際、リセハウジングとプラグの内壁同士を合わせる様に位置決めした後に押し込み嵌合して下さい。  
 斜めの嵌合になる場合は 10°以下の角度でリセハウジングとプラグの内壁同士を軽く当て、位置決めした後に平行にしてから嵌合して下さい。(図-2)  
 尚、リセハウジングの外壁とプラグ外壁とを当てた(支点とした)状態で嵌合を行いますと、反支点側のリセハウジングとプラグの内壁同士が干渉し、ハウジングの破壊およびピン損傷の恐れがありますのでこのような嵌合は避け下さい。(図-3)

[Mating]

Mate connectors parallel to the mating axis as much as possible. (Figure-1)  
 In doing so, priory determine the position with temporary fitting each inner wall of the Receptacle and Plug housing, then mate those fully.  
 If angled mating is inevitable, determine the position priory with temporary fitting each inner wall of the Receptacle and Plug housing softly within an angle less than 10 degree, and mate the connector parallel. (Figure-2)  
 Avoid from mating connectors with fitting each outer wall of Receptacle and Plug housing as a supporting point because the each inner wall on the opposite side could interfere each other and cause housing or pin breakage. (Figure-3)

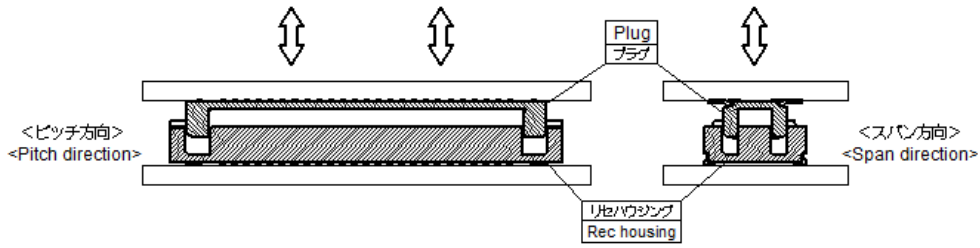
[抜去]

抜去は極力嵌合軸に沿って平行に行ってください。(図-1)  
 または、左右に少しずつ振りながら行って下さい。(図-4)  
 (過度のこじり抜去には注意して下さい。ハウジングの破壊およびピン損傷の原因となります。)(図-5)

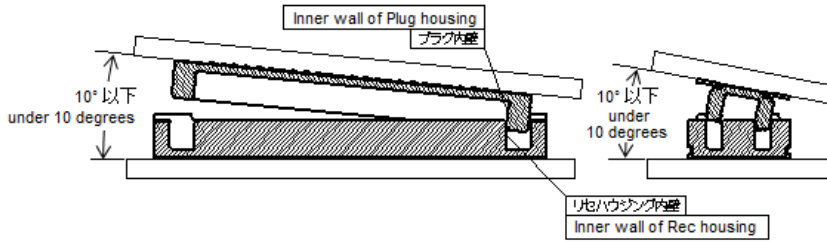
[Withdrawal]

Withdraw the connector parallel to mating axis as much as possible (Figure-1).  
 Or do it with slightly swinging them right to left. (Figure-4)  
 (Please take care NOT to do excess twist extraction. It could cause the housing or pin breakage.) (Figure-5)

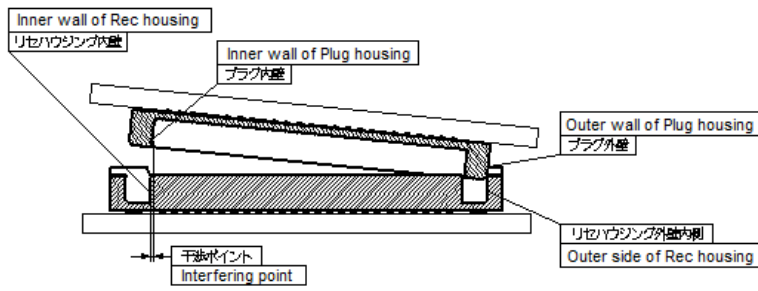
|                              |                   |  |                  |                     |                   |
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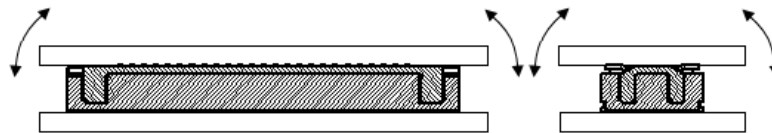
○ 図-1 平行状態での挿抜 (Best)  
Figure-1 Horizontal Mating/Unmating



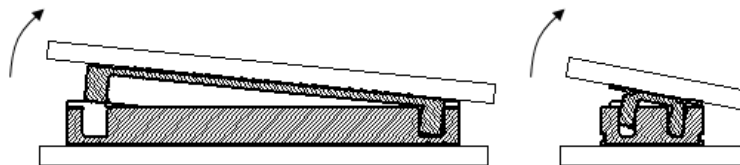
△ 図-2 内壁合せによる嵌合 (Acceptable)  
Figure-2 Mating aligning to inner wall of housings



× 図-3 外壁合せによる嵌合 (Not Good)  
Figure-3 Mating aligning to outer wall of housings



○ 図-4 抜去 (Best)  
Figure-4 Withdrawal



× 図-5 こじり抜去 (Not Good)  
Figure-5 Withdrawal with twisting the connector at an angle

|                              |                   |  |                     |                   |
|------------------------------|-------------------|--|---------------------|-------------------|
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【9. 取り扱い上の注意事項 INSTRUCTION UPON USAGE】

・外観について Appearance

1. 本製品の樹脂部に黒点、多少の傷、微小な気泡等が生じることがありますが、性能上問題ありません。また、本製品のモールド材料はLCPを使用しているため、ウェルドラインが目立つ場合がありますが、製品性能には影響ないものです。  
Although this product may have a small black dot, a scratch and minimum air bubble on the housing, it doesn't impact the product's performance. Also, although weld line may stand out due to LCP used to mold material of this product, it doesn't impact the product's performance.
2. 成形品の色相に多少の違いを生じる場合がありますが、製品性能には影響ありません。  
Although there may be slight differences in the housing color tone, it doesn't impact the product's performance.
3. 紫外線によりハウジングが変色する場合がありますが、製品性能に影響ありません。  
Although the housing color tone could be changed by ultraviolet light, it doesn't impact the product's performance.
4. 本製品の錫めっきを使用しているため、外観に摺動痕がつく場合が御座いますが、製品性能に影響はありません。  
Although the surface of the product could have scratch marks by frictions because of the Tin plating, it doesn't impact the product's performance.

・実装について Mount

5. 本リフロー条件に関しては、実装条件(大気、N2 リフロー/温度プロファイル/半田ペースト/メタルマスク板厚/開口率/基板パターンレイアウト/実装基板種別などの種々の要素)により条件が異なりますので、必ずご使用前に、顧客様のご使用環境で事前に実装評価(リフロー評価)を実施願います。実装条件によっては、接点部への半田上がりやフラックス上りが発生するなど製品性能に影響を及ぼす場合があります。  
Please make sure to do test run under the mounting condition (reflow soldering condition) on your own devices before use because reflow condition may change due to the local condition (Air reflow, N2 reflow / temperature profile / solder paste/ metal mask thickness / metal mask aperture rate / pattern layout of PWB / types of PWB / and other factors ). Depending on the mounting condition, product's performance might be influenced by occurrence of solder-wicking or flux wicking at contact area.
6. 本製品の一般性能確認はリジッド基板にて実施しております。フレキシブル基板等の特殊な基板へ実装する場合は、事前に実装確認等を行った上でご使用願います。  
The product performance was tested using rigid PWB. In case the product needs to be mounted onto FPC, please conduct a reflow test on the FPC before use.
7. フレキシブル基板に実装する場合は、基板の変形を防止するため、補強板をご使用願います。  
In case of mounting the connector onto FPC, add a stiffener on the FPC in order to prevent the deformation.

|                              |                   |   |                              |                     |                   |
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8. 本コネクタを搭載する基板(PWB/FPC)において、過度な温度上昇を避ける為、適切なパターンデザインを行ってください。  
Please design appropriate pattern on boards (PWB / FPC) for this connector to avoid excess temperature rise.
9. 弊社の推奨基板パターン寸法を変更して設計を行なう際は、致命的な不良の原因にもなりますので、あらかじめご相談ください。  
In case of designing with changing our recommended board pattern size, please consult the contact person in advance because it may cause a fatal defect.
10. 実装性能(平坦度)は、実装基板の反りの影響を含まないものと致します。基板の反りはコネクタ両端部を基準とし、コネクタ中央部にて Max0.02mm として下さい。  
The mounting specification for coplanarity does not include the influence of warpage of the PWB. Warpage of the PWB should be 0.02mm at maximum at center of the connector based on the both sides of connector.
11. 本製品は大気リフローでの実装を想定しています。N2 リフローで実装した場合、リフロー後、半田上がりを生じる恐れがあります。N2 リフローでの実装をお考えの場合、別途評価が必要になります。  
This product is designed to be mounted by air reflow. So, if this product is mounted by N2 reflow, solder wicking may caused after reflow. Therefore if it is plan to adopt N2 reflow for this connector, an evaluation is needed separately.
12. 弊社評価では本仕様書記載の推奨条件に基づき評価を実施しています。  
Our evaluation is conducted based on Molex-recommended condition specified in this product specification.
13. 本製品の平坦度については、実装前での保証のみであり、実装中および実装後での平坦度については、保証の限りではありません。  
Only coplanarity before reflow is guaranteed. Coplanarity in and after reflow is not guaranteed.
14. 本製品は端子先端部に、カット面がある為に端子先端部の実装性(基板への半田付け性)は、端子側面・後側に比べて悪くなります。しかし、側面及び後側においてフィレットが形成されていれば、機能及び強度に問題はありません。  
The solderability of the terminal tip, which is cut surface without plating, is worse than the sides/back of the terminal with plating. However, it will not impact the product's function or the retention force if good soldering fillet is formed at the sides/back of the terminal.
15. 製品仕様上、テール上面まで半田濡れ上がりはありませんが、製品性能上問題ありません。  
Although the top surface of tail does not get wet with solder, due to the product specification, it does not impact on the product's performance.

|                              |                   |  |                  |                     |                   |
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16. 半田実装部の未半田は、ターミナル脱落、ピン間ショート、ターミナル座屈、またコネクタの基板からの外れが懸念されます。従って全てのターミナルテール部及び、ネイル部に半田付けを行って下さい。  
If you leave any soldering area on this product open, it could occur terminal disengagement, short circuit between pins, terminal buckling or connector disengagement from the PWB. Therefore, please solder all of the soldering tails and fitting nails on the PWB.
17. 実装機によってコネクタに負荷が加わると変形、破損する場合がありますので事前にご確認下さい。  
If accidental contact is added onto connectors in the reflow machine, connectors could be deformed or damaged. Therefore review the reflow machine before use of the connectors.
18. リフロー条件によっては、樹脂部の変色や端子めっき部にヨリが発生する場合がありますが、製品性能に影響はございません。  
Although color tone of housing or surface of terminal plating could be varied depending on reflow conditions, it does not impact on the product's performance.

**・製品の仕様について Product specification**

19. 本製品をご使用時には、1PIN 当りの定格以上の電流を複数の回路に分岐しての使用は避けて下さい。  
When using this product, ensure that the specification for rated current per a circuit is followed. Do not allow the sum of the current used on several circuits to exceed the maximum allowable current.
20. 本製品をご使用時に取り付けられた電線・プリント基板の共振や、機器の回転構造や可動部分の動作によりコネクタ嵌合部(接点部)が常に動いてしまう状態での御使用は避けて下さい。接触部の摺動磨耗等による接触不良の原因となります。従って、機器内で電線・プリント基板を固定し、共振を抑える等の処置をお願い致します。  
Do not use the connector in a condition where the mating area (contact area) are constantly moved due to sympathetic vibration of wires and PWB or constant movement of devices. It may cause contact failure due to the worn out. Therefore fix wires and PWB on the chassis to reduces sympathetic vibration.
21. コネクタに外力が加わらないようにクリアランスをあけた筐体構造にして下さい。  
Keep enough clearance between connector and chassis of your application in order to avoid pressure on the connector.
22. 本製品を結露・水濡れが発生する環境でのご使用の場合は、適切な防滴処置をお願い致します。結露・水濡れにより、回路間で絶縁不良を起こす可能性が御座います。  
When using this product in an environment where dew condensation and water wetting occur, apply an appropriate drip-proof treatment. Dew condensation and water wetting could cause insulation failure between the circuits.
23. コネクタのみで基板を支えることは避け、コネクタ以外での基板固定対策を行ってください。  
Avoid using a connector alone to mechanically support the PWB. Adopt separate fixture to support PWB besides the connector in the chassis.

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- 24. 活電状態の電気回路で、挿入、抜去ができることを前提に作られていません。スパーク等による危険の発生、性能不良につながりますので、活電状態での挿入、抜去はしないで下さい。  
Do not mate and un-mate connectors while those are energized since this connector is not designed to allow it. It may cause danger due to sparks and functional failure of the product.
- 25. 一枚の基板にコネクタを複数実装する場合は、嵌合相手側はそれぞれ個別の基板に実装してご使用をお願いします。  
When mounting several board to board connectors on a same PWB, ensure to mount the each mating connector on a separate PWB.
- 26. 本製品及び加工工程品(仕掛品)や加工品(ハーネス品)の梱包及び輸送・保管時において、コネクタ間での絡みや衝撃、積み重ね等による負荷が掛からないようにして下さい。変形・破損等による性能不良の原因となります。  
At packaging, transportation and storing, avoid applying loads to connectors by handling, interference of connectors or piling-up packages. It could cause functional defect such as connector deformation or breakage.
- 27. 推奨保管条件での保管をお願い致します。もし、梱包品の推奨保管条件を超えてしまった場合は外観、半田付け性を確認の上ご使用ください。  
Store the products under recommended storage condition. If the recommended storage conditions of the packaging is exceeded, check the appearance of the products and solder-wettability before use.
- 28. 基板実装後に基板を直接積み重ねない様に注意してください。  
Do not stack PWB directly after mounting the connector on it.
- 29. コネクタの性能を損なう恐れがある為、コネクタの洗浄は、行わないで下さい。  
Do not wash connector because it may impact the product's function.
- 30. 通電による実際の温度上昇値は、通電条件や筐体設計、使用基板などによる影響を受けますので、予め使用環境をご確認ください。  
Actual value of temperature rise depends on the electric current condition, design of application, PWB design etc., Please confirm use situation in advance.

**・製品操作について Product operation**

- 31. 基板実装前後に端子、補強金具に触らないでください。  
Do not touch the terminals and fitting nails of connectors before or after mounting onto the PWB.
- 32. 嵌合後、コネクタピッチ方向、スパン方向及び回転方向への負荷がかかるような動作またはセットはしないでください。コネクタ破壊やはんだクラックを引き起こします。Avoid move or assembly of connector which could apply loads to the direction of the connector pitch, span or rotation. It may damage the connector and crack the soldering.

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- 33. ハウジングのロック部やランス部などの可動部、及び端子を故意に変形させないで下さい。製品性能が満足出来ない原因となります。  
Do not purposely deform the movable parts such as housing lock or lance and terminals. It may impact the product performance.
- 34. 嵌合の際、嵌合が不十分にならないようご注意ください。また、セットへの組み込み後も、振動、衝撃等で嵌合の浮きが発生しないような状態にて使用してください。  
Ensure to mate connectors fully. Also mount and assemble the connector in your application unit with disengagement proof to avoid connector disengagement due to vibration or shocks.

**・リペアについて Repair**

- 35. 実装後において半田ゴテによる手修正を行う際は、必ず仕様書掲載の条件以内で行って下さい。条件を超えて実施した場合、端子の抜け、接点ギャップの変化、モールドの変形、溶融等、破損の原因になります。  
When conducting manual repairs using a soldering iron, follow the soldering conditions shown in the product specification. If the conditions in the product specification are not followed, it may cause the terminal disengagement, contact gap change, housing deformation, housing melting, and connector damage.
- 36. 半田ゴテによる手修正を行なう際、過度の半田やフラックスを使用しないで下さい。半田上がりやフラックス上がりにより接触、機能不良に至る場合があります。  
When conducting manual repairs using a soldering iron, do not use excess solder and flux than needed. It may cause solder wicking and flux wicking issues, and also eventually cause a contact defect and functional issues.

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